



# Product Change Notification

**Change Notification #:** 116436 - 00  
**Change Title:** Intel® Spare Drive Bays & Carrier Options FXX35HSCAR2, PCN 116436-00, Product Design, Update 3.5" tool less carriers design to improve hard to push out (stuck) in S2600WF Family  
**Date of Publication:** August 16, 2018

## Key Characteristics of the Change:

Product Design

## Forecasted Key Milestones:

<b>Date Customer Must be Ready to Receive Post-Conversion Material*:</b>	August 31, 2018
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\* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

## Description of Change to the Customer:

Intel is updating the Intel® Spare Drive Bays & Carrier Options FXX35HSCAR2 to improve the mobility of the carrier when removing from the chassis, by adding a groove on the carrier frame to avoid hook touching edge (See below images).

All new components perform the same operation with improvements on their design.

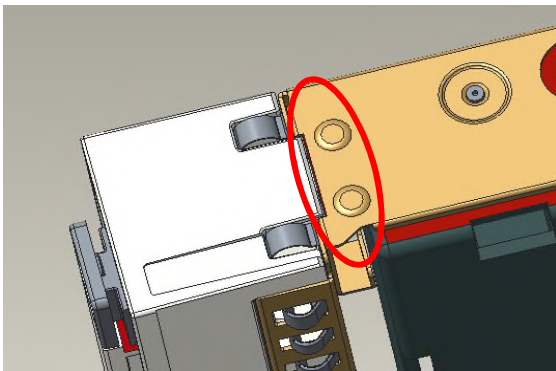


Figure 1: Previous Shape

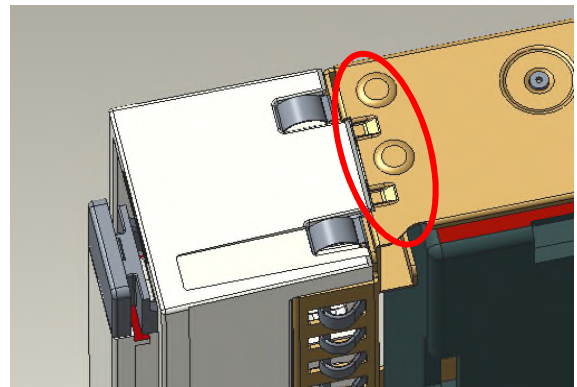


Figure 2: New shape with groove

## Customer Impact of Change and Recommended Action:

Intel does not expect any impact to customers from these changes, but encourages customers to understand the change and determine the impact on their applications.

## Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Post Change TA
FXX35HSCAR2	958245	J37328-001	J37328-002

## PCN Revision History:

**Date of Revision:**

August 16, 2018

**Revision Number:**

00

**Reason:**

Originally Published PCN



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**Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.**

**Americas Contact:** [asmo.pcn@intel.com](mailto:asmo.pcn@intel.com)

**Asia Pacific/PRC Contact:** [apagccb@intel.com](mailto:apagccb@intel.com)

**Europe Email:** [eccb@intel.com](mailto:eccb@intel.com)

**Japan Email:** [jccb.ijkk@intel.com](mailto:jccb.ijkk@intel.com)

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